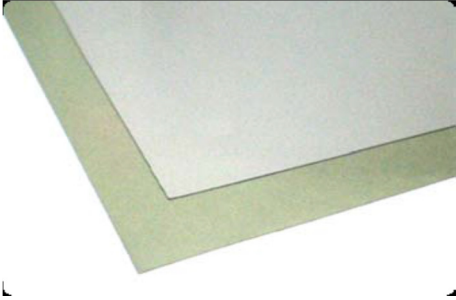


Thin Silicone Thermal Pad MPN Series



AMEC Thermasol MPN series of thermal filler pads are extremely thin yet with 5W/mk high thermal conductivity. Its soft characteristic also provides cushioning and excellent gap-filling properties. Can be supplied in sheets, rolls and custom die cut shapes.

Features

- 5W/mk High thermal conductivity
- Low thermal Resistance
- Conformable, low hardness
- Electrically Isolating
- High breakdown voltage

Applications

- CPU, GPU (Notebooks, Desktops, Servers)
- Memory
- Display (LED, LCD, PDP etc)
- Custom ASICS Chips
- LED Applications
- Digital Mobile
- Telecommunication Equipment

Item	Unit	Value	Standard
Thermal Conductivity	W/mK	5	ASTM D5470
Thermal Resistance	°C.in ² /W	0.13 (0.5mm) 0.29 (1.0mm)	ASTM D5470
Thickness	mm	0.5,1.0	
Hardness	Shore 00	40~80	ASTM D2240
Breakdown Voltage	kV	5.8	ASTM D149
Volume Resistance	Ω.cm	6.1x10 ¹¹	ASTM D257
Density	g/cm ³	3.0	ASTM D792
Flammability rating	-	94 V-0	UL
Operating Temperature	°C	-40~150	-
ROHS	-	Non detected	-

Part Number system –

Series – Thermal Conductivity /Shore Hardness-Sheet size

E.g.: MPN-5040-150x300x0.5

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